



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	26-07-2023
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32C031C4T6 STM32C031C4T6R	725B*453XXXZ	A	998Z	26-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	178.13	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7	48	L bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	725B*453XXZ				5999949.0	899958.1
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.568	mg	supplier	die	Silicon (Si)	7440-21-3		2.468	mg	961059	13855
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1947	28
				supplier	metallization	Copper (Cu)	7440-50-8		0.042	mg	16355	236
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.014	mg	5452	79
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	389	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	4283	62
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	10514	152
				Supplier	Metals	Silver (Ag)	7440-22-4		0.285	mg	815000	1602
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.011	mg	30000	59
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.011	mg	30000	59
Glue epoxy (3230)	M-011 Other inorganic materials	0.350	mg	Supplier	Organic Compounds	Maleic anhydride	108-31-6		0.011	mg	30000	59
				Supplier	Organic Compounds	Dodecyloxirane	3234-28-4		0.011	mg	30000	59
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.011	mg	30000	59
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.011	mg	30000	59
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.002	mg	5000	10
				Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.567	mg	21000	14413
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.567	mg	21000	14413
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.847	mg	56000	38435
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		95.419	mg	780450	535655
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		14.099	mg	115320	79149
Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	122.261	mg	Supplier	Non-metals	Carbon Black	1333-86-4		0.762	mg	6230	4276
				Supplier	Metals	Gold (Au)	7440-57-5		0.865	mg	1000000	4855
				Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	6054
				Supplier	Metals	Copper (Cu)	7440-50-8		49.589	mg	972200	278379
				Supplier	Metals	Iron ( Fe )	7439-89-6		1.158	mg	22700	6500
				Supplier	Metals	Zinc ( Zn )	7440-66-6		0.077	mg	1500	430
				Supplier	Non-Metals	Phosphorus ( P )	7723-14-0		0.015	mg	300	86
				Supplier	Metals	Silver (Ag)	7440-22-4		0.166	mg	3250	931
				Supplier	Metals	Gold (Au)	7440-57-5		0.865	mg	1000000	4855
				Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	6054
Bonding Wire (Au)	Bonding Wire	0.865	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.865	mg	1000000	4855
External plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	6054
Leadframe (C194 + Ag)	Copper & its alloys	51.007	mg	Supplier	Metals	Copper (Cu)	7440-50-8		49.589	mg	972200	278379
				Supplier	Metals	Iron ( Fe )	7439-89-6		1.158	mg	22700	6500
				Supplier	Metals	Zinc ( Zn )	7440-66-6		0.077	mg	1500	430
				Supplier	Non-Metals	Phosphorus ( P )	7723-14-0		0.015	mg	300	86
				Supplier	Metals	Silver (Ag)	7440-22-4		0.166	mg	3250	931